

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 06/13/2022

**Details for "UCC28950QPWRQ1"**

**Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
UCC28950QPWRQ1	NIPDAU	Level-1-260C-UNLUM	TI TAIWAN A/T	PW   24	7.7x4.4x1.0	149

\*Total Device Mass  
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

**Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

**Component Information**

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.000296	3	0.000001	0
Other Nonferrous Metals and Alloys	Calcium	7440-70-2	0.000001	0.000296	3	0.000001	0
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.000002	0.000592	6	0.000001	0
Precious Metals	Gold	7440-57-5	0.337848	99.997632	999976	0.226719	2267
Precious Metals	Silver	7440-22-4	0.000004	0.001184	12	0.000003	0
Sub-Total			0.337856	100	1000000	0.226724	2267
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	0.348648	69.99994	699999	0.233966	2340
Thermoplastics	Epoxy	85954-11-6	0.149421	30.00006	300001	0.100272	1003
Sub-Total			0.498069	100	1000000	0.334238	3342
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	87.646826	97.049999	970500	58.816965	588170
Copper and Its Alloys	Iron	7439-89-6	2.348086	2.6	26000	1.575725	15757
Copper and Its Alloys	Phosphorus	7723-14-0	0.135467	0.150001	1500	0.090908	909
Zinc and Its Alloys	Zinc	7440-66-6	0.180622	0.2	2000	0.12121	1212
Sub-Total			90.311001	100	1000000	60.604807	606048
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	0.298677	95.120064	951201	0.200433	2004
Precious Metals	Gold	7440-57-5	0.002449	0.779936	7799	0.001643	16
Precious Metals	Palladium	7440-05-3	0.012874	4.1	41000	0.008639	86
Sub-Total			0.314	100	1000000	0.210715	2107
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	47.446362	85.499999	855000	31.839727	318397
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	1.664785	3.000001	30000	1.117184	11172
Other Organic Materials	Chlorine	7782-50-5	0.011099	0.020001	200	0.007448	74
Other Plastics and Rubber	Carbon Black	1333-86-4	0.166478	0.299999	3000	0.111718	1117
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.055493	0.1	1000	0.03724	372
Thermoplastics	Epoxy	85954-11-6	6.148605	11.080001	110800	4.126131	41261
Sub-Total			55.492822	100	1000000	37.239448	372394
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	2.062485	100	1000000	1.384067	13841
Sub-Total			2.062485	100	1000000	1.384067	13841
<b>Total</b>			149.016233			100	1000000

**Important Note**

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.  
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.  
[See Glossary of Terms for more details.](#)

**Important Part Information**

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

**Product Content Methodology**

[For an explanation of the methods used to determine material weights. See Product Content Methodology](#)

**Material Declaration Certificate for Semiconductor IC Packaged Products**

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

**Important Information/Disclaimer**

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

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[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.